



# 650V SuperJunction Power MOSFET

## Features

- Extremely Low Gate Charge
- Excellent Output Capacitance ( $C_{oss}$ ) Profile
- Fast Switching Capability
- Ultra Fast Body Diode
- 100% UIS Tested, 100%  $R_g$  Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant
- AEC-Q101 Qualified for Automotive Applications

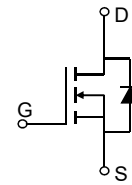
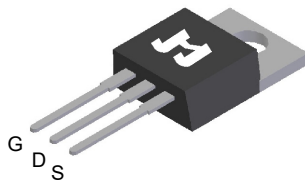
## Product Summary

Parameter	Value	Unit
$V_{DS}$	650	V
$V_{GS(th\_Typ)}$	3.5	V
$I_D$ (@ $V_{GS} = 10V$ ) <sup>(1)</sup>	20	A
$R_{DS(ON\_Typ)}$ (@ $V_{GS} = 10V$ )	170	mΩ
$E_{oss@400V}$	5.2	μJ

## Applications

- Unidirectional and bidirectional DC-DC converters
- On-Board battery Chargers

TO-220-3L Top View

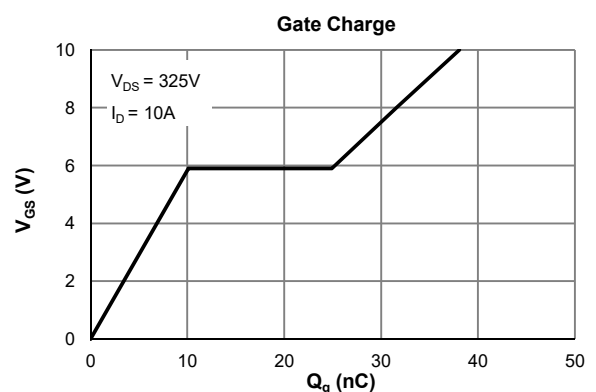
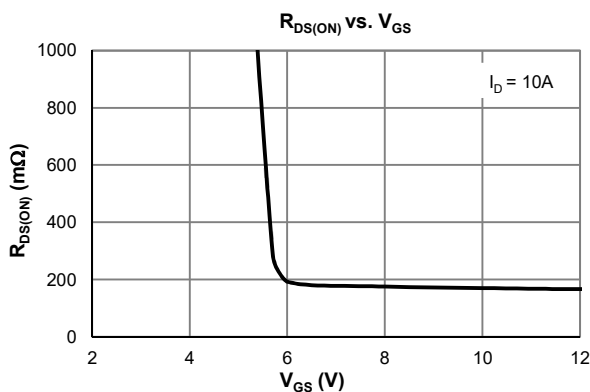


## Ordering Information

Device	Package	# of Pins	Marking	MSL	$T_J$ (°C)	Media	Quantity (pcs)
JMH65R190ACFDQ-U	TO-220-3L	3	65R190AFQ	NA	-55 to 150	Tube	50

## Absolute Maximum Ratings (@ $T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DS}$	650	V
Gate-to-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	$T_C = 25^\circ C$	20
		$T_C = 100^\circ C$	12.1
Pulsed Drain Current <sup>(2)</sup>	$I_{DM}$	75	A
Avalanche Current <sup>(3)</sup>	$I_{AS}$	9.0	A
Avalanche Energy <sup>(3)</sup>	$E_{AS}$	405	mJ
Power Dissipation <sup>(4)</sup>	$P_D$	$T_C = 25^\circ C$	189
		$T_C = 100^\circ C$	76
Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C





**Electrical Characteristics** (@ T<sub>J</sub> = 25°C unless otherwise specified)

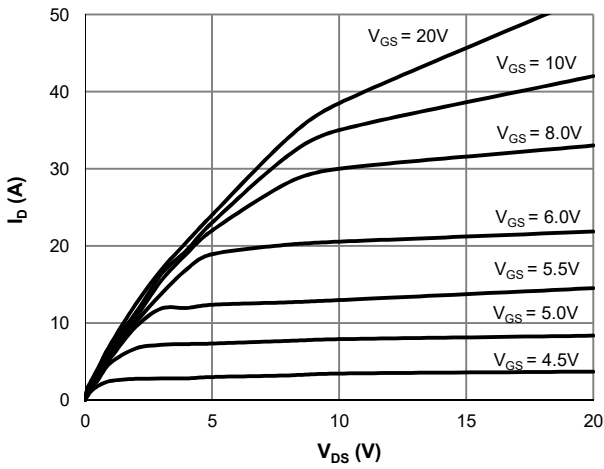
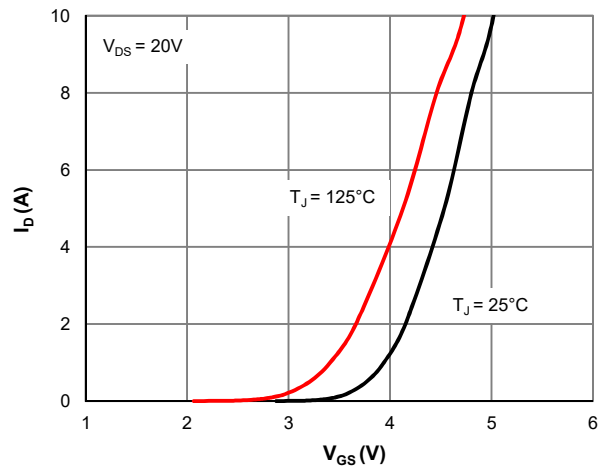
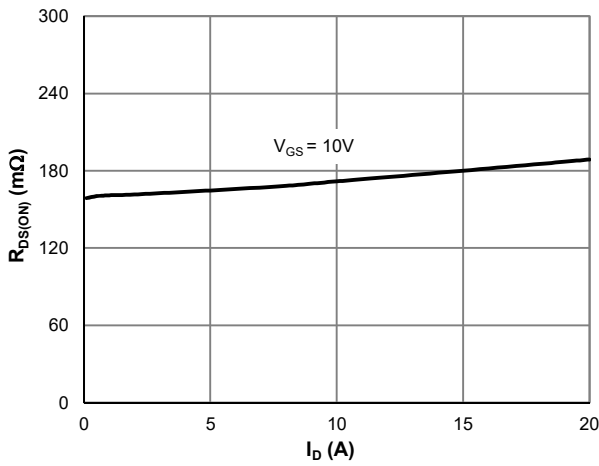
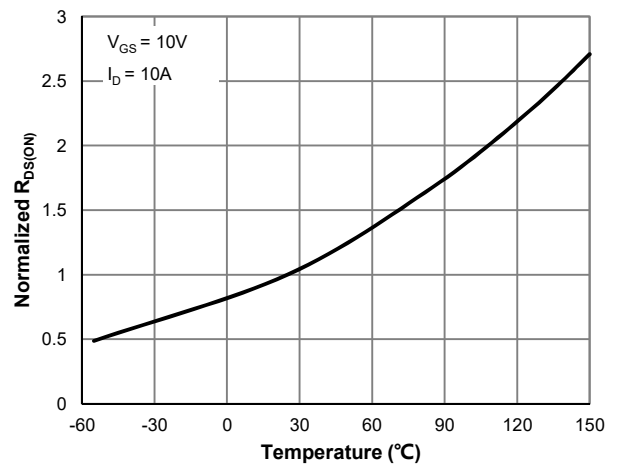
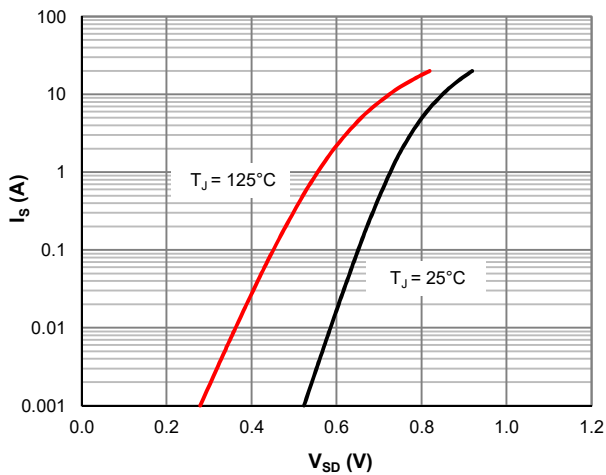
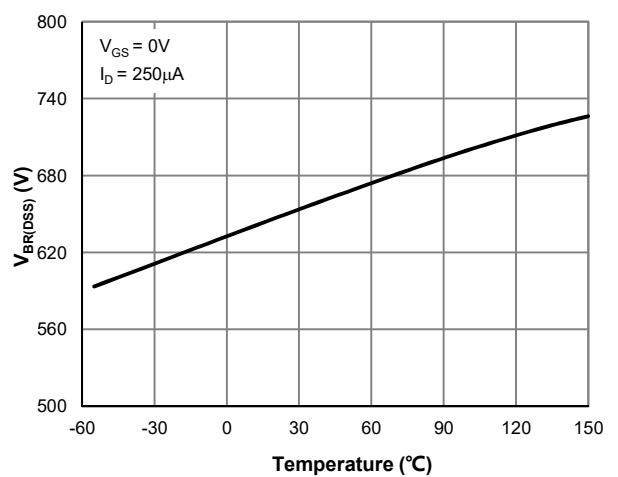
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	650			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V			1.0	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±30V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5	3.5	4.5	V
Static Drain-Source ON-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A		170	190	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V		0.75	1.0	V
Diode Continuous Current	I <sub>S</sub>	T <sub>C</sub> = 25°C			189	A
<b>DYNAMIC PARAMETERS <sup>(5)</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V, f = 1MHz		1560		pF
Output Capacitance	C <sub>oss</sub>			61		pF
Reverse Transfer Capacitance	C <sub>riss</sub>			11.7		pF
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0 to 400V		65		pF
Effective output capacitance, time related	C <sub>o(tr)</sub>			274		pF
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz		8.9		Ω
<b>SWITCHING PARAMETERS <sup>(5)</sup></b>						
Total Gate Charge (@ V <sub>GS</sub> = 10V)	Q <sub>g</sub>	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 325V, I <sub>D</sub> = 10A		38		nC
Gate Source Charge	Q <sub>gs</sub>			10.1		nC
Gate Drain Charge	Q <sub>gd</sub>			14.8		nC
Turn-On DelayTime	t <sub>D(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 325V R <sub>L</sub> = 3.25Ω, R <sub>GEN</sub> = 6Ω		17.8		ns
Turn-On Rise Time	t <sub>r</sub>			22		ns
Turn-Off DelayTime	t <sub>D(off)</sub>			257		ns
Turn-Off Fall Time	t <sub>f</sub>			20		ns
Body Diode Reverse Recovery Time	t <sub>rr</sub>		I <sub>F</sub> = 10A, di <sub>F</sub> /dt = 100A/μS		122	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 10A, di <sub>F</sub> /dt = 100A/μS		715		nC
Peak Diode Recovery Voltage Slope	dv/dt	I <sub>F</sub> ≤ 10A, di <sub>F</sub> /dt = 200A/us, V <sub>DS</sub> = 400V		50		V/ns
MOSFET dv/dt Ruggedness	dv/dt	V <sub>DS</sub> = 0...400V		50		V/ns

**Thermal Performance**

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	42	50	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.66	0.80	°C/W

**Notes:**

1. Computed continuous current assumes the condition of T<sub>J\_Max</sub> while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under T<sub>J\_Max</sub> = 150°C.
3. This single-pulse measurement was taken under the following condition [L = 10mH, V<sub>DD</sub> = 10V, V<sub>DS</sub> = 50V] while its value is limited by T<sub>J\_Max</sub> = 150°C.
4. The power dissipation P<sub>D</sub> is based on T<sub>J\_Max</sub> = 150°C.
5. This value is guaranteed by design hence it is not included in the production test.

**Typical Electrical & Thermal Characteristics**

**Figure 1: Saturation Characteristics**

**Figure 2: Transfer Characteristics**

**Figure 3:  $R_{DS(ON)}$  vs. Drain Current**

**Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature**

**Figure 5: Body-Diode Characteristics**

**Figure 6:  $V_{BR(DSS)}$  vs. Junction Temperature**

Typical Electrical & Thermal Characteristics

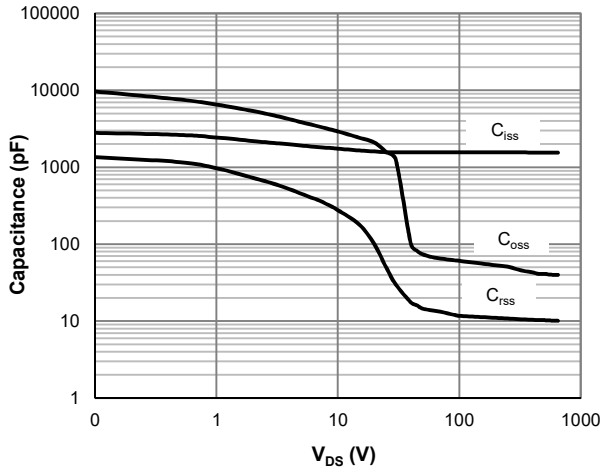


Figure 7: Capacitance Characteristics

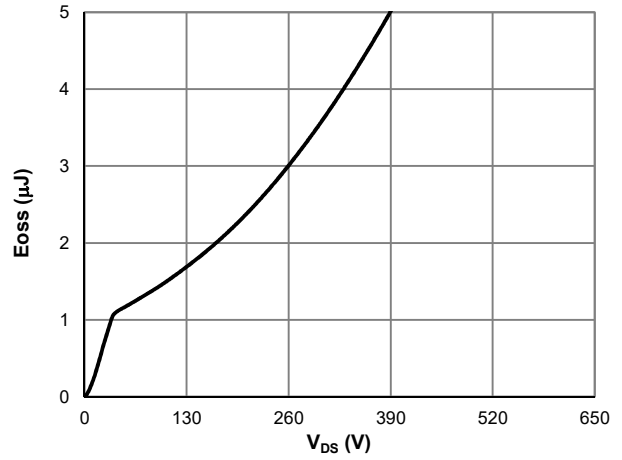


Figure 8: Coss Stored Energy

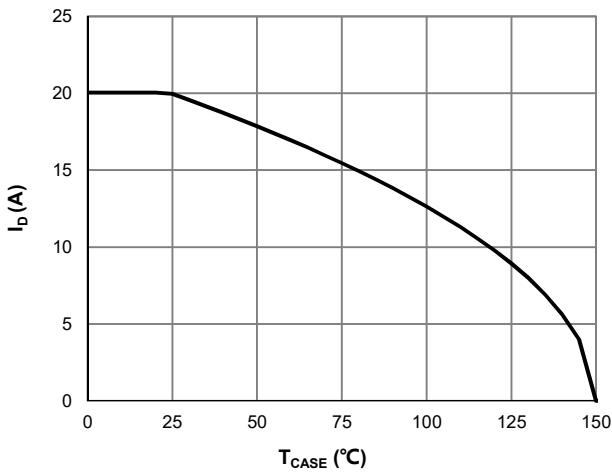


Figure 9: Current De-rating

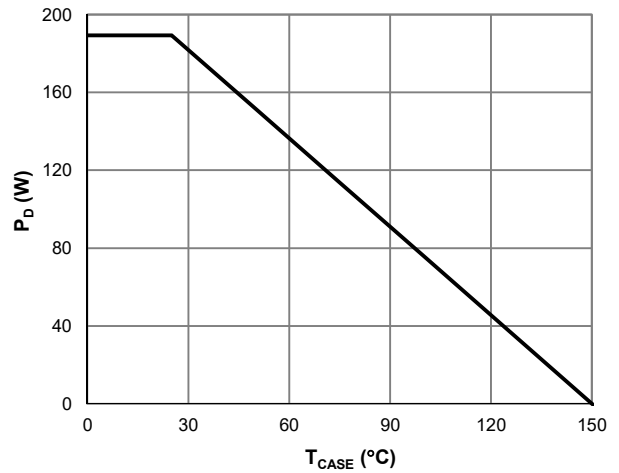


Figure 10: Power De-rating

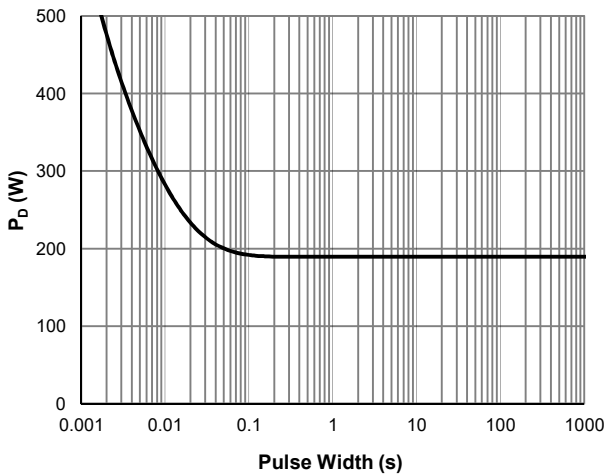


Figure 11: Single Pulse Power Rating, Junction-to-Case

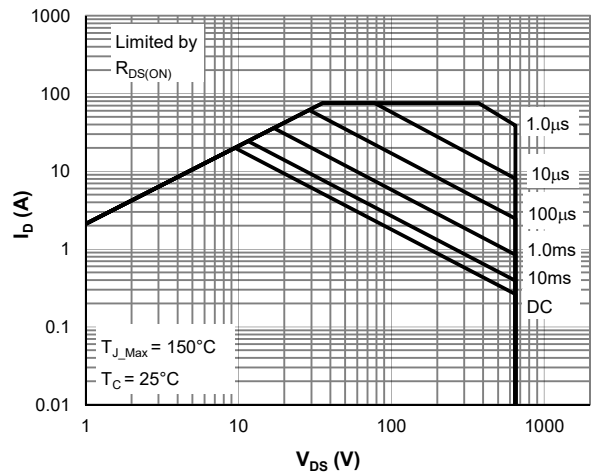


Figure 12: Maximum Safe Operating Area



### Typical Electrical & Thermal Characteristics

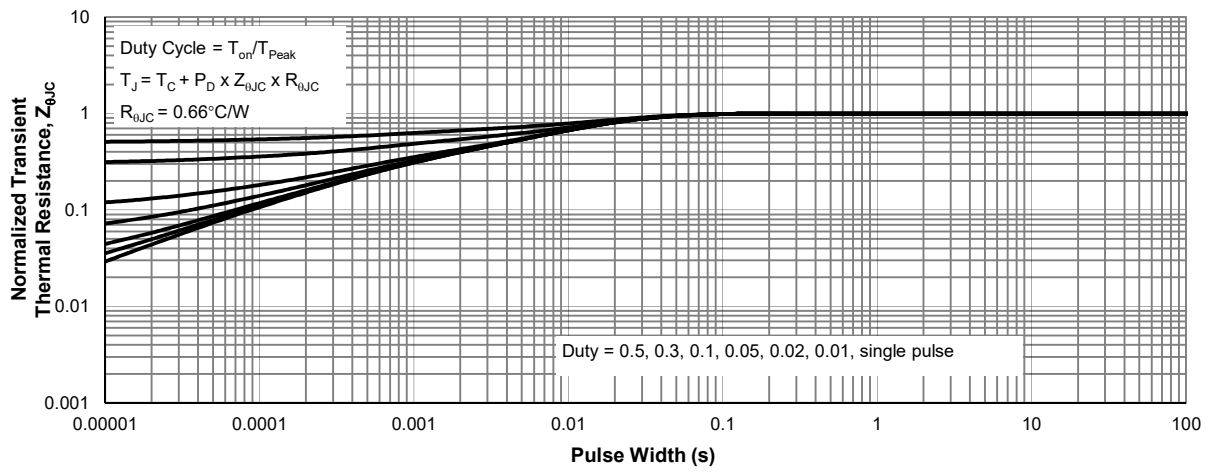
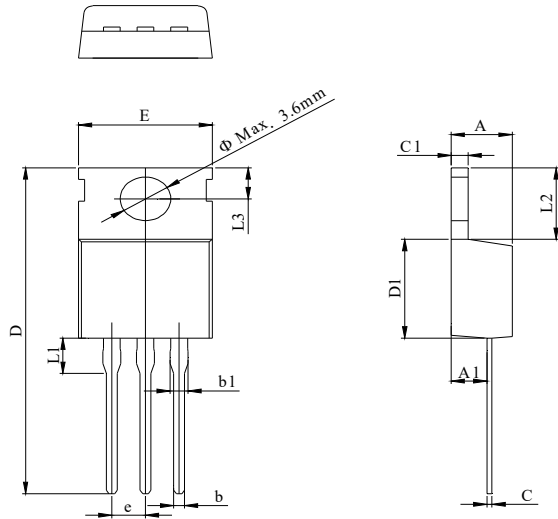


Figure 13: Normalized Maximum Transient Thermal Impedance



TO-220-3L Package Information

Package Outline



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.24		4.70
A1	2.20		3.00
b	0.70		0.95
b1	1.14		1.70
C	0.40		0.60
C1	1.15		1.40
D	28.00		29.80
D1	8.80		9.90
E	9.70		10.50
L1			3.80
L2	6.25		6.90
L3	2.40		3.00
e		2.54 BSC	